

UPWARDS Summer Intensive Program 2026– Information Sheet

Host University	Hiroshima University
Program Title	Hiroshima University UPWARDS Summer Intensive Program 2026 – Peace and Semiconductor Innovation
Program Period (Dates)	12 days from 2026, July 22 to August 2
Location & Venue	Hiroshima University (Higashi-Hiroshima campus) Higashi-Hiroshima City, Japan
Maximum Enrollment from Partner Universities	Up to 22 participants in total: 12 students from U.S. partner universities (2 students from each of 6 universities), 5 students from 4 Japanese partner universities, and 5 students from Hiroshima University.
Program Fee	\$2500USD per student
Requirements	Students currently enrolled in undergraduate or graduate programs at a UPWARDS member university are eligible to apply.
Application Method & Deadline	Application document should be submitted to Hiroshima University through applicant’s university. Deadline to send in nomination: Feb. 27 th 2026
Curriculum Overview	<p>The Hiroshima University UPWARDS Summer School 2026 – “Peace and Semiconductor Innovation” is a 12-day interdisciplinary program combining peace learning in Hiroshima with hands-on semiconductor training at the Research Institute for Semiconductor Engineering (RISE).</p> <p>Participants will gain both scientific and cultural perspectives, exploring how technology and innovation contribute to a sustainable and peaceful society.</p> <p>Program Overview</p> <p>Week 1 – Orientation & Industry Engagement</p> <ul style="list-style-type: none"> • Welcome & Orientation at Hiroshima University • Campus Tour and Networking with Tokyo Electron (TEL) • Visit to Micron Memory Japan • Free weekend for self-guided activities <p>Week 2 – Semiconductor Training & Regional Collaboration</p> <ul style="list-style-type: none"> • CMOS Practical Training at RISE (Layout Design, Process Lecture & Cleanroom Tour, Measurement) • Peace Study at Hiroshima Peace Memorial Park • Visit to Saijo City, Ehime Prefecture • Shimanami Kaido Island-Hopping Tour • Networking with CMOS participants and industry partners <p>Final Day</p> <ul style="list-style-type: none"> • Student Presentations • Closing Ceremony & Farewell Party
Acquirable Competencies (Multiple selections allowed)	<input type="checkbox"/> Competency 1 - Foundational Knowledge in Semiconductor Engineering <input checked="" type="checkbox"/> Competency 2 - Foundational Knowledge in Semiconductor Industry and Business <input type="checkbox"/> Competency 3 - Ability to Manage/Understand Diversity, Equity and Inclusion

	<input checked="" type="checkbox"/> Competency 4 - Gain Global/Inter-Cultural Competencies including International Mindset, Inter- Cultural Competence, Collaboration and Teamwork, Communication Skills, and Leadership <input checked="" type="checkbox"/> Competency 5 - Hands-on Experiences of Semiconductor Industry Operations <input type="checkbox"/> Competency 6 - Research Application Skills
Study Hours	Full 8 days of structured program (lectures, hands-on labs, and networking sessions), equivalent to approximately 80 total study hours, designed to achieve Competencies 2, 4, and 5.
Information about Accommodation	Hiroshima University will provide accommodation for all participants during the 12-day summer school.
Program Coordinator	Dr. Linh Cao
Contact Information	<p>Academic Contact Dr. Linh Cao Research Institute for Semiconductor Engineering (RISE), Hiroshima University Email: linhthuycao(at)hiroshima-u.ac.jp</p> <p>Administrative Contacts Ms. Watanabe, Mr. Miyagaki Global Strategy Group, Hiroshima University Email: kokusai-group(at)office.hiroshima-u.ac.jp</p>
Program Website & Other Information	Refer to HU flyer